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IN THE ABSTRACT:

Please amend the abstract of the application as follows.

A stencil for the deposition of a heat yieldable joining material includes at least one pattern formation member and at least one channel formation portion associated with the pattern formation member. A method of coupling circuit board assembly and electronic components includes providing a circuit board, where the circuit board includes at least one component pad and a via extending through at least one layer of the circuit board; providing an electronic component; disposing a joining material mask on the via; forming a joining material pattern on the component pad, the joining material pattern including an out-gassing channel; and heating the circuit board assembly and electronic component.